

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

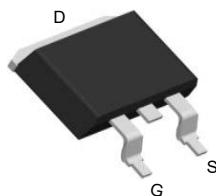
Product Summary



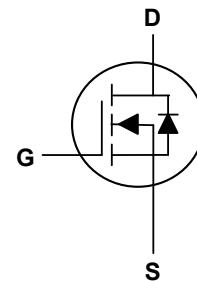
| | | |
|----------------------------------|-----|----|
| V_{DS} | 60 | V |
| I_D | 140 | A |
| $R_{DS(ON)}$ (at $V_{GS}=10V$) | 5.2 | mΩ |
| $R_{DS(ON)}$ (at $V_{GS}=4.5V$) | 7 | mΩ |

Applications

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



TO-263 Top View



Absolute Maximum Ratings($T_c=25^\circ C$, unless otherwise noted)

| Parameter | Symbol | Rating | Units |
|--|---------------------------|------------|-------|
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current, $V_{GS} @ 10V^1$ | $I_D @ T_c = 25^\circ C$ | 140 | A |
| Continuous Drain Current, $V_{GS} @ 10V^1$ | $I_D @ T_c = 100^\circ C$ | 90 | A |
| Pulsed Drain Current ² | I_{DM} | 300 | A |
| Single Pulse Avalanche Energy ³ | EAS | 125 | mJ |
| Avalanche Current | I_{AS} | 50 | A |
| Total Power Dissipation ⁴ | $P_D @ T_c = 25^\circ C$ | 166 | W |
| Storage Temperature Range | T_{STG} | -55 to 150 | °C |
| Operating Junction Temperature Range | T_J | -55 to 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Unit |
|--|-----------------|-----|------|------|
| Thermal Resistance Junction-Ambient ¹ | $R_{\theta JA}$ | --- | 62 | °C/W |
| Thermal Resistance Junction-Case ¹ | $R_{\theta JC}$ | --- | 0.75 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|----------------------------|---|-----|------|-----------|------------------|
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$ | 60 | --- | --- | V |
| Static Drain-Source On-Resistance ² | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=10\text{V}$, $I_D=30\text{A}$ | --- | 4.3 | 5.2 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}$, $I_D=20\text{A}$ | --- | 6 | 7 | $\text{m}\Omega$ |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$ | 1.2 | --- | 2.5 | V |
| Drain-Source Leakage Current | I_{DSS} | $V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$ | --- | --- | 1 | uA |
| | | $V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$ | --- | --- | 5 | |
| Gate-Source Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |
| Forward Transconductance | g_{fs} | $V_{\text{DS}}=10\text{V}$, $I_D=30\text{A}$ | --- | 75 | --- | S |
| Gate Resistance | R_g | $V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 0.7 | --- | Ω |
| Total Gate Charge | Q_g | $V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=25\text{A}$ | --- | 75 | --- | nC |
| Gate-Source Charge | Q_{gs} | | --- | 15.5 | --- | |
| Gate-Drain Charge | Q_{gd} | | --- | 20.3 | --- | |
| Turn-On Delay Time | $T_{\text{d}(\text{on})}$ | $V_{\text{DD}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$, $I_D=30\text{A}$ | --- | 18.5 | --- | ns |
| Rise Time | T_r | | --- | 8.8 | --- | |
| Turn-Off Delay Time | $T_{\text{d}(\text{off})}$ | | --- | 58.8 | --- | |
| Fall Time | T_f | | --- | 15.8 | --- | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 4706 | --- | pF |
| Output Capacitance | C_{oss} | | --- | 325 | --- | |
| Reverse Transfer Capacitance | C_{rss} | | --- | 245 | --- | |

Drain-Source Diode Characteristics

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|-----------------|--|-----|------|-----|-------------|
| Continuous Source Current ^{1,5} | I_s | $V_G=V_D=0\text{V}$, Force Current | --- | --- | 140 | A |
| Diode Forward Voltage ² | V_{SD} | $V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$ | --- | --- | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $I_F=30\text{A}$, $di/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$ | --- | 22.9 | --- | nS |
| | | | --- | 11.6 | --- | nC |

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

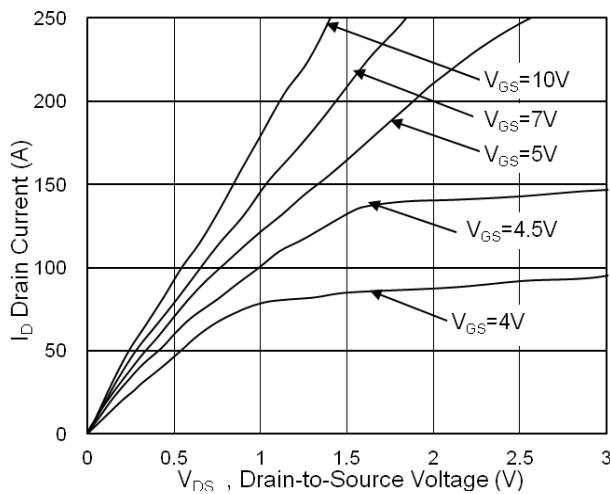


Fig.1 Typical Output Characteristics

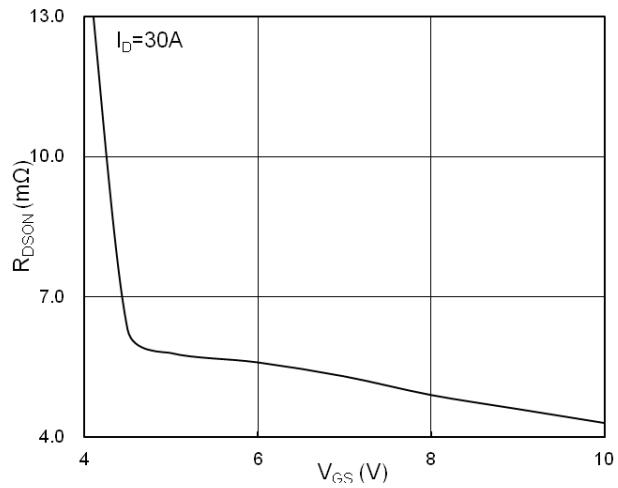


Fig.2 On-Resistance v.s Gate-Source

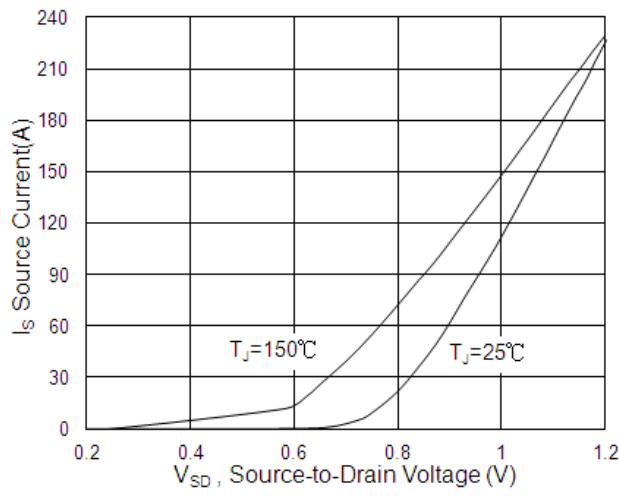


Fig.3 Forward Characteristics of Reverse

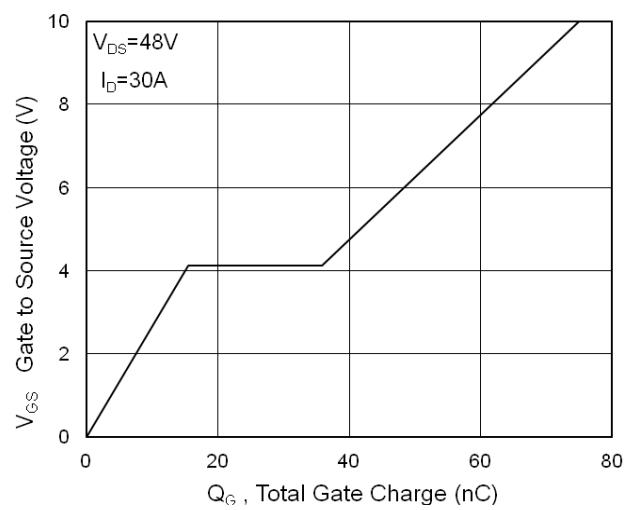


Fig.4 Gate-Charge Characteristics

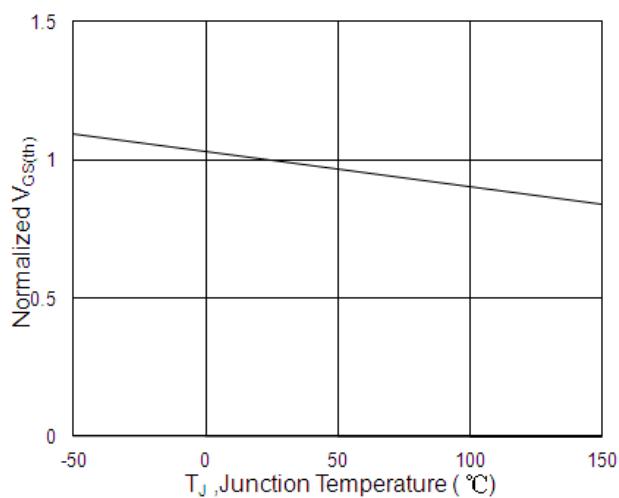


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

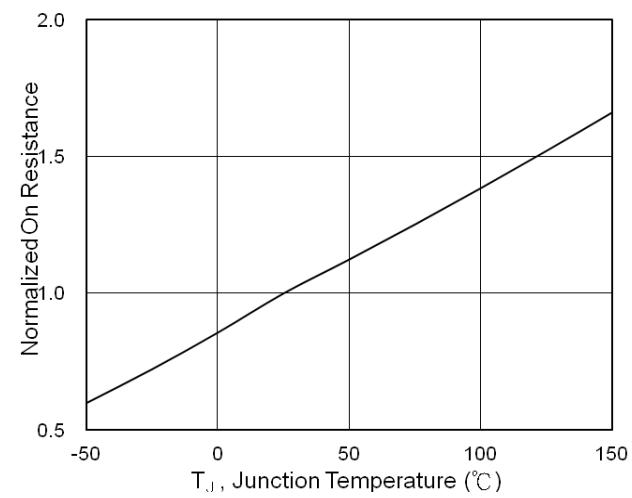
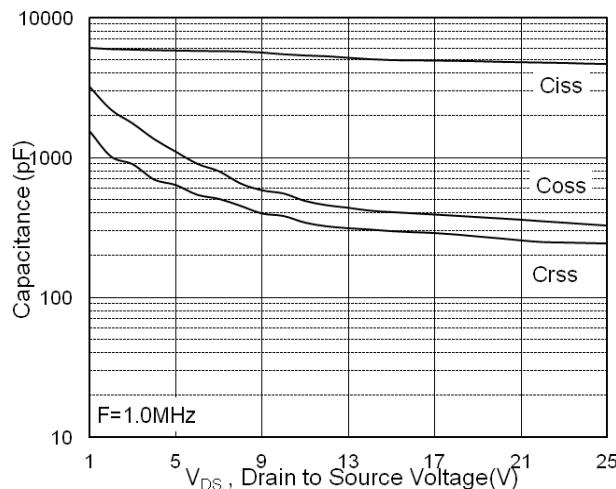
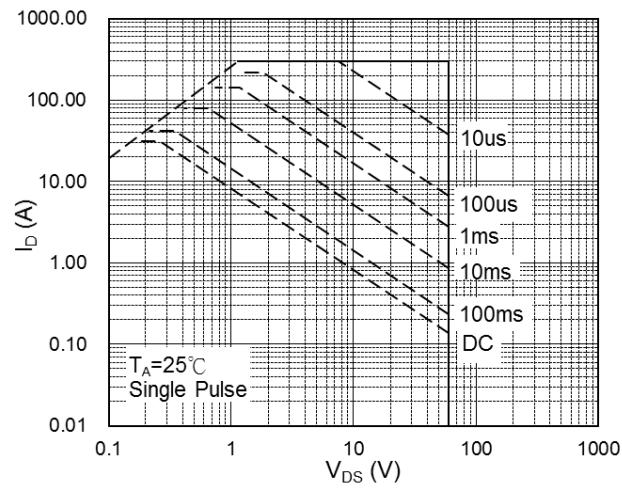
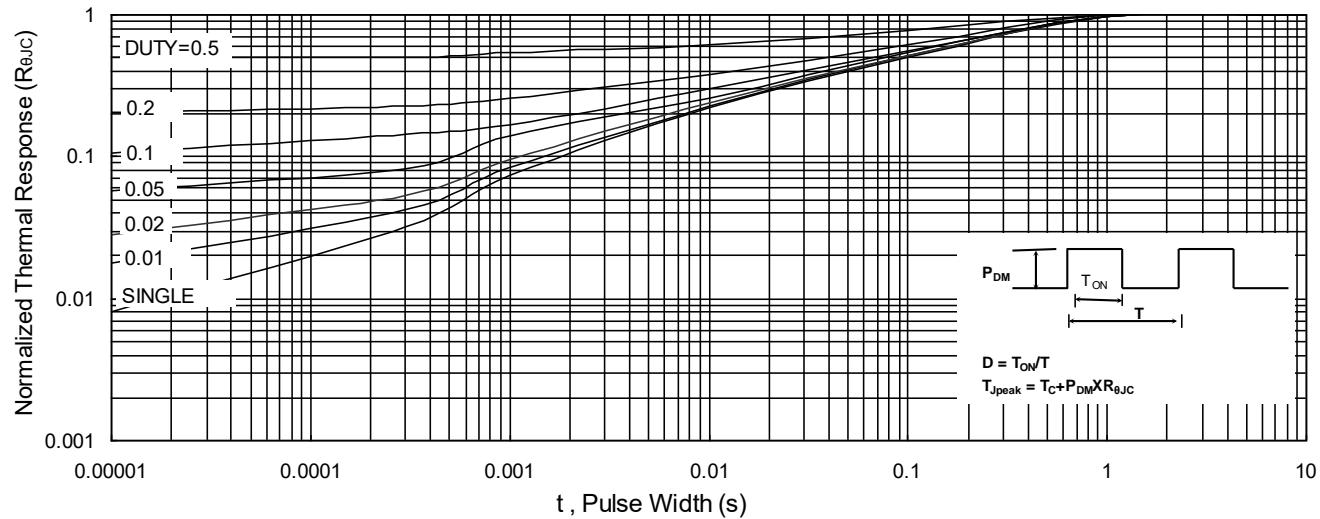
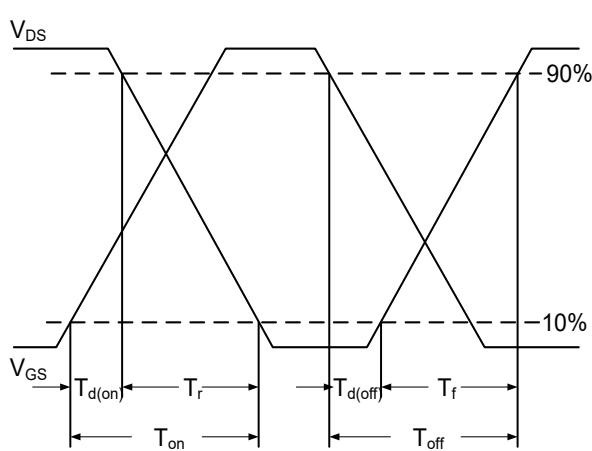
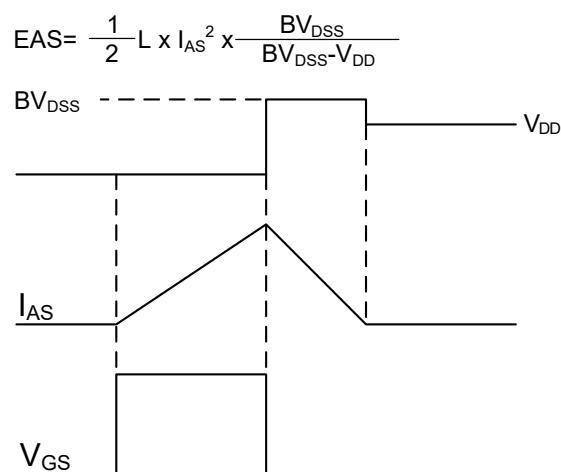
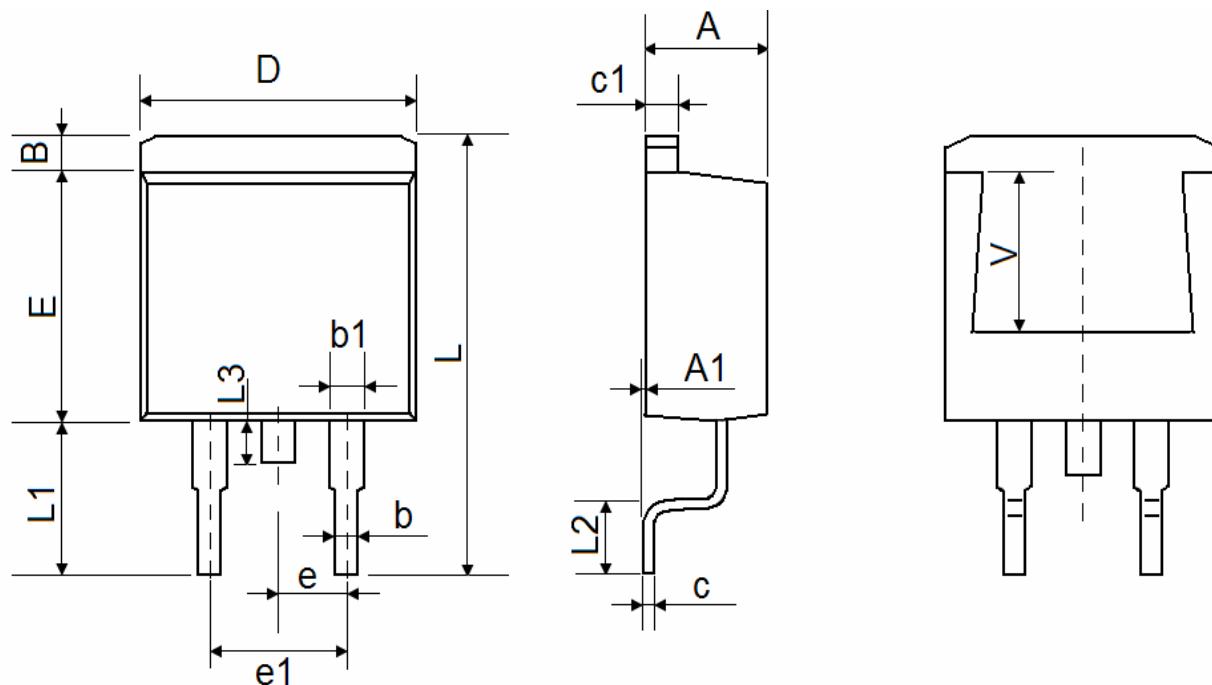


Fig.6 Normalized $R_{DS(on)}$ vs. T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform

TO-263 Package Outline Dimensions



| Symbol | Dimensions (unit:mm) | | | Symbol | Dimensions (unit:mm) | | |
|--------|----------------------|------|------|--------|----------------------|-------|-------|
| | Min | Typ | Max | | Min | Typ | Max |
| A | 4.40 | 4.55 | 4.70 | A1 | 0.00 | 0.07 | 0.15 |
| B | 1.00 | 1.20 | 1.40 | b | 0.65 | 0.80 | 0.95 |
| b1 | 1.10 | 1.15 | 1.37 | c | 0.30 | 0.40 | 0.53 |
| c1 | 1.10 | 1.25 | 1.37 | D | 9.80 | 10.00 | 10.40 |
| E | 8.50 | 8.80 | 9.20 | e | 2.54 REF | | |
| e1 | 4.90 | 5.10 | 5.40 | L | 14.80 | 15.20 | 15.70 |
| L1 | 5.00 | 5.25 | 5.60 | L2 | 2.05 | 2.45 | 2.80 |
| L3 | 1.20 | 1.50 | 1.80 | V | 5.60 REF | | |